ABSTRACT

INTEGRATED CIRCUIT DEVICE AND METHOD FOR MANUFACTURING SAME

According to one embodiment, an integrated circuit device includes a plurality of interconnects and a contact via. The plurality of interconnects are arranged parallel to each other. The contact via is connected to each of the interconnects. A protrusion is formed at a portion of the each of the interconnects connected to the contact via to protrude in a direction of the arrangement. A recess is formed at a portion of the each of the interconnects separated from the portion having the protrusion to recede in the direction of the arrangement. The protrusion formed on one interconnect of two mutually-adjacent interconnects among the plurality of interconnects is opposed to the recess formed in one other interconnect of the two mutually-adjacent interconnects. In the each of the interconnects, the portion having the recess is separated from portions on two sides of the portion having the

FIG. 2

162162

G00002